

## *Triac (Bidirectional Triode Thyristor)*

### Features and Benefits

- Exceptional reliability
- Small fully-molded SIP package with heatsink mounting for high thermal dissipation and long life
- $V_{DRM}$  of 400 or 600 V
- 20  $A_{RMS}$  on-state current
- Uniform switching
- UL Recognized Component (File No.: E118037) (suffix I)



**Package: 3-pin SIP (TO-220F)**



*Not to scale*

### Description

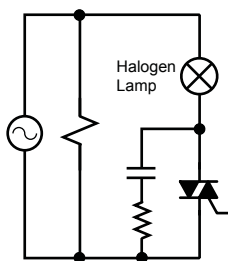
This Sanken triac (bidirectional triode thyristor) is designed for AC power control, providing reliable, uniform switching for full-cycle AC applications.

In comparison with other products on the market, the TMA20x series provides increased isolation voltage (1800  $V_{AC_{RMS}}$ ), guaranteed for up to 1 minute, and greater peak nonrepetitive off-state voltage,  $V_{DSM}$  (700 V). In addition, commutation  $dv/dt$  and  $(dv/dt)_c$  are improved.

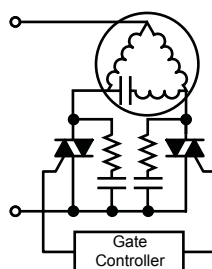
### Applications

- Residential and commercial appliances: vacuum cleaners, rice cookers, TVs, home entertainment
- White goods: washing machines
- Office automation power control, photocopiers
- Motor control for small tools
- Temperature control, light dimmers, electric blankets
- General use switching mode power supplies (SMPS)

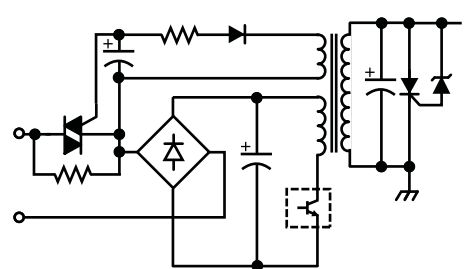
### Typical Applications



Heater control  
(for example, LBP, PPC, MFP)



Two-phase motor control  
(for example, washing machine)



In-rush current control  
(for example, SMPS)

## Selection Guide

Part Number	V <sub>DRM</sub> (V)	UL-Recognized Component	Package	Packing
TMA204(I)	400	Yes	3-pin fully molded SIP with heatsink mount	50 pieces per tube
TMA204S-L	400	—		
TMA206(I)	600	Yes		
TMA206S-L	600	—		

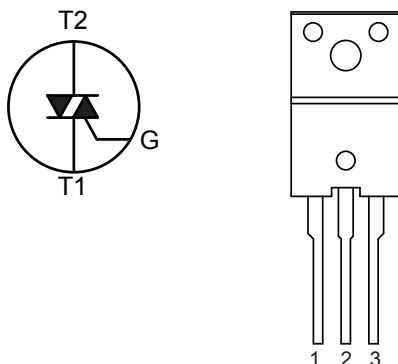
## Absolute Maximum Ratings

Characteristic	Symbol	Notes		Rating	Units
Peak Repetitive Off-State Voltage	V <sub>DRM</sub>	TMA204x	R <sub>GREF</sub> = ∞	400	V
		TMA206x		600	V
Peak Non-Repetitive Off-State Voltage	V <sub>DSM</sub>	TMA204x	R <sub>GREF</sub> = ∞	500	V
		TMA206x		700	V
Isolation Voltage	V <sub>ISO</sub>	AC RMS applied for 1 minute between lead and case		1800	V
RMS On-State Current	I <sub>T(RMS)</sub>	50/60 Hz full cycle sine wave, total Conduction angle (α+) + (α−) = 360°, T <sub>C</sub> = 53°C		20	A
Surge On-State Current	I <sub>TSM</sub>	f = 60 Hz	Full cycle sine wave, peak value, non-repetitive, initial T <sub>J</sub> = 125°C	200	A
		f = 50 Hz		190	A
I <sup>2</sup> t Value for Fusing	I <sup>2</sup> t	Value for 50 Hz half cycle sine wave, 1 cycle, I <sub>TSM</sub> = 190 A		180	A <sup>2</sup> •s
Peak Gate Current	I <sub>GM</sub>	f ≥ 50 Hz, duty cycle ≤ 10%		2	A
Peak Gate Power Dissipation	P <sub>GM</sub>	f ≥ 50 Hz, duty cycle ≤ 10%		5	W
Average Gate Power Dissipation	P <sub>GM(AV)</sub>	T <sub>J</sub> < T <sub>J(max)</sub>		0.5	W
Junction Temperature	T <sub>J</sub>			−40 to 125	°C
Storage Temperature	T <sub>stg</sub>			−40 to 125	°C

## Thermal Characteristics May require derating at maximum conditions

Characteristic	Symbol	Test Conditions	Value	Units
Package Thermal Resistance (Junction to Case)	R <sub>θJC</sub>	For AC	3.2	°C/W

## Pin-out Diagram



Terminal List Table

Number	Name	Function
1	T1	Main terminal, gate referenced
2	T2	Main terminal connect to signal side
3	G	Gate control

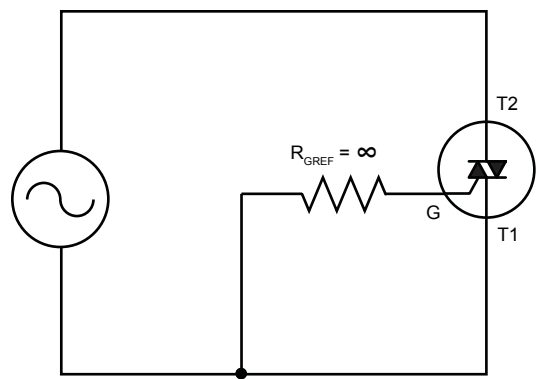
All performance characteristics given are typical values for circuit or system baseline design only and are at the nominal operating voltage and an ambient temperature, T<sub>A</sub>, of 25°C, unless otherwise stated.

ELECTRICAL CHARACTERISTICS

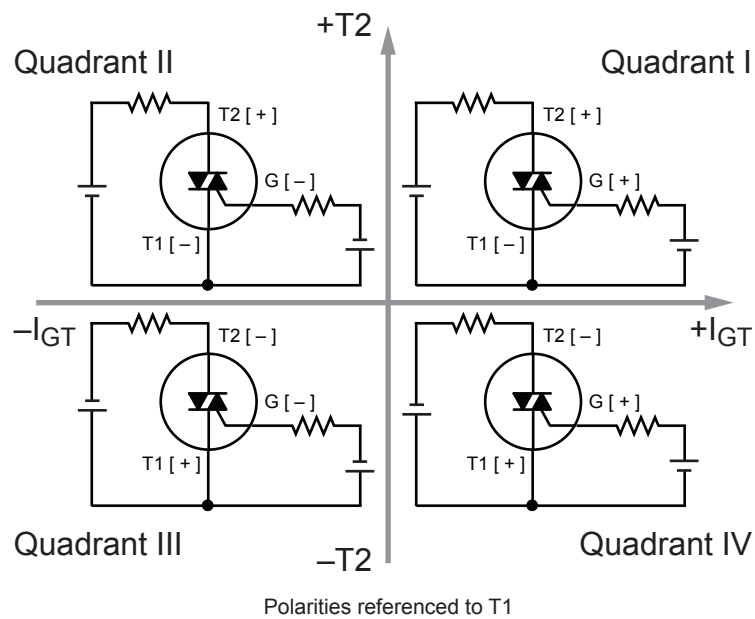
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Off-State Leakage Current	$I_{\text{DRM}}$	$V_{\text{D}} = V_{\text{DRM}}$ , $T_{\text{J}} = 125^{\circ}\text{C}$ , $R_{\text{GREF}} = \infty$ using test circuit 1	–	–	2.0	mA
		$V_{\text{D}} = V_{\text{DRM}}$ , $T_{\text{J}} = 25^{\circ}\text{C}$ , $R_{\text{GREF}} = \infty$ using test circuit 1	–	–	100	$\mu\text{A}$
On-State Voltage	$V_{\text{TM}}$	$I_{\text{T}} = 20\text{ A}$ , $T_{\text{J}} = 25^{\circ}\text{C}$	–	–	1.5	V
Gate Trigger Voltage	$V_{\text{GT}}$	Quadrant I: T2+, G+	–	–	1.5	V
		Quadrant II: T2+, G–	–	–	1.5	V
		Quadrant III: T2–, G–	–	–	1.5	V
Gate Trigger Current	$I_{\text{GT}}$	Quadrant I: T2+, G+	–	–	30	mA
		Quadrant II: T2+, G–	–	–	30	mA
		Quadrant III: T2–, G–	–	–	30	mA
Gate Non-trigger Voltage	$V_{\text{GD}}$	$V_{\text{D}} = V_{\text{DRM}} \times 0.5$ , $R_{\text{L}} = 4\text{ k}\Omega$ , $T_{\text{J}} = 125^{\circ}\text{C}$	0.2	–	–	V
Critical Rising Rate of Off-State Voltage during Commutation*	$(\text{d}v/\text{d}t)_{\text{c}}$	$T_{\text{J}} = 125^{\circ}\text{C}$ , $V_{\text{D}} = 400\text{ V}$ , $(\text{d}i/\text{d}t)_{\text{c}} = -10\text{ A/ms}$ , $I_{\text{TP}} = 2\text{ A}$	10	–	–	$\text{V}/\mu\text{s}$

\*Where  $I_{\text{TP}}$  is the peak current through T2 to T1.

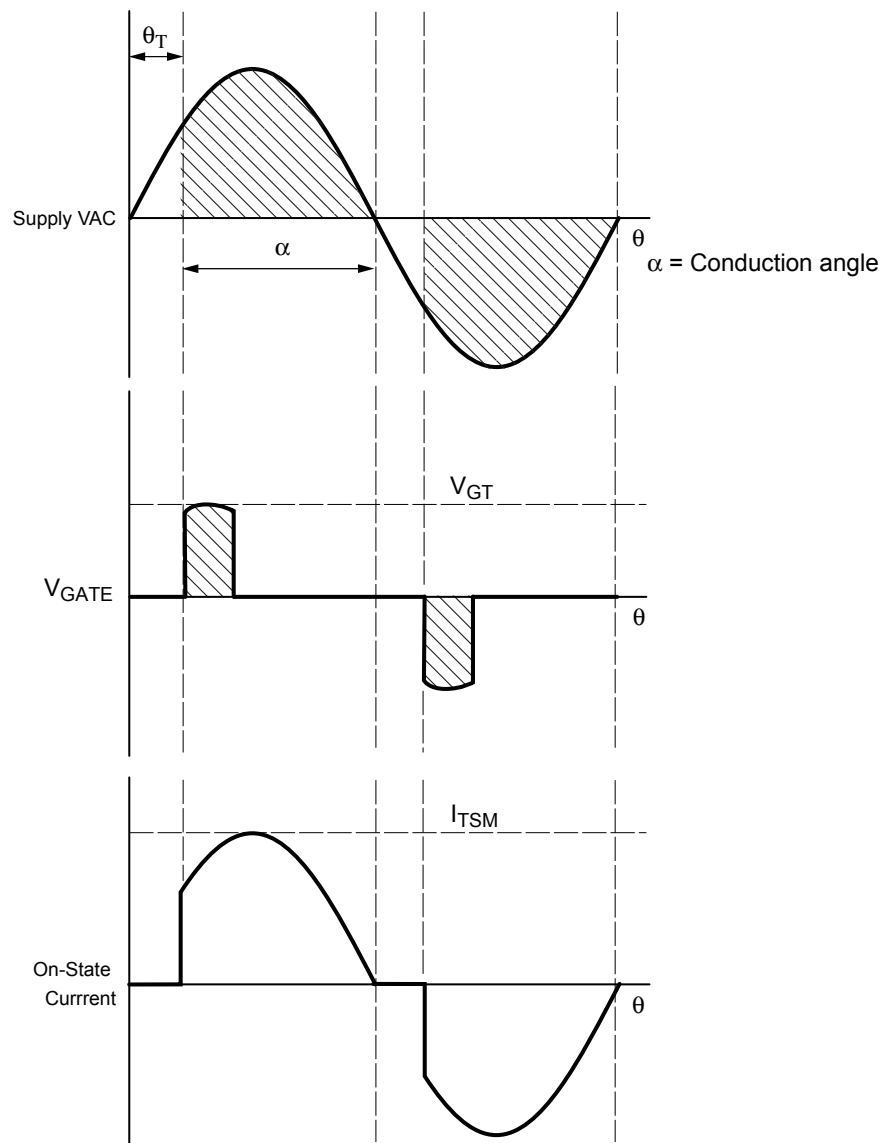
Test Circuit 1

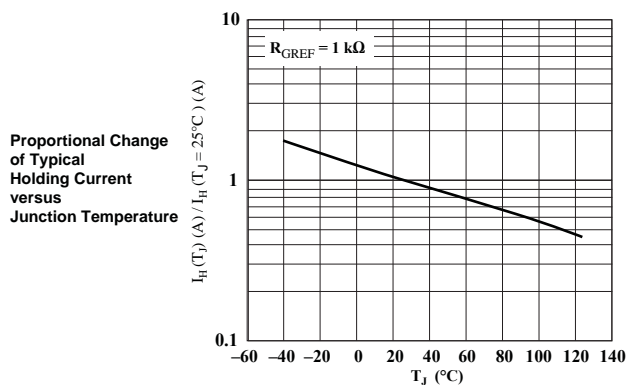
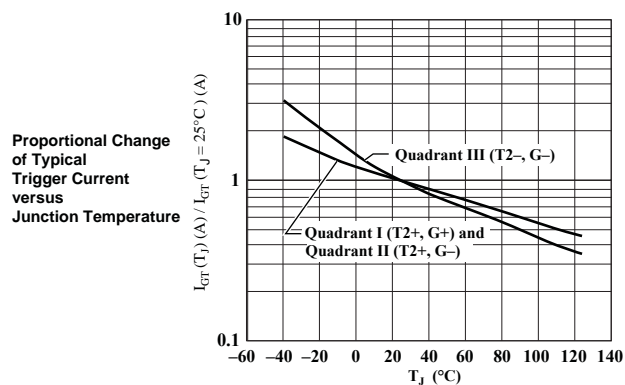
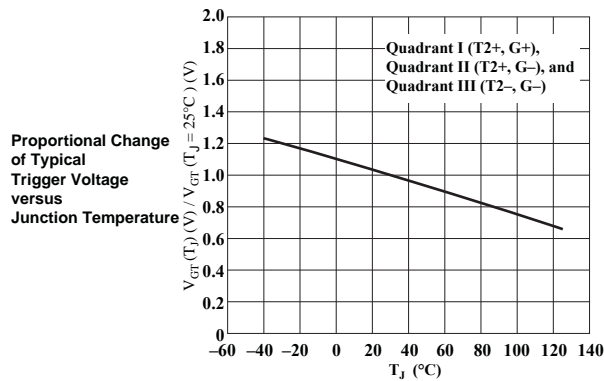
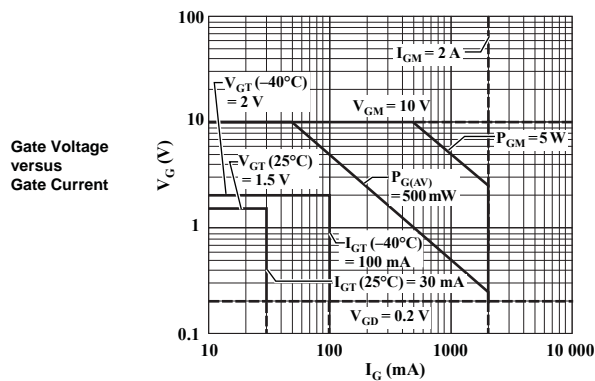
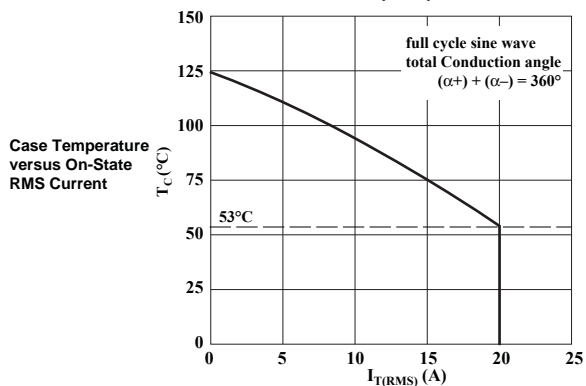
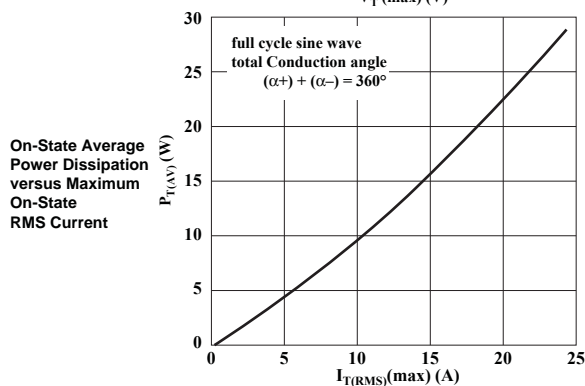
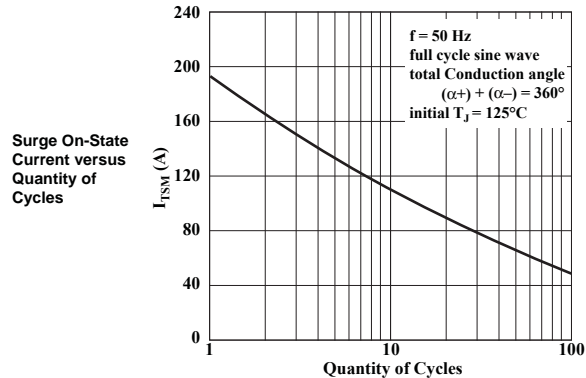
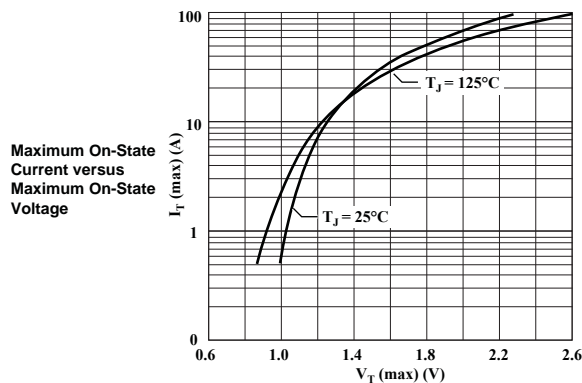


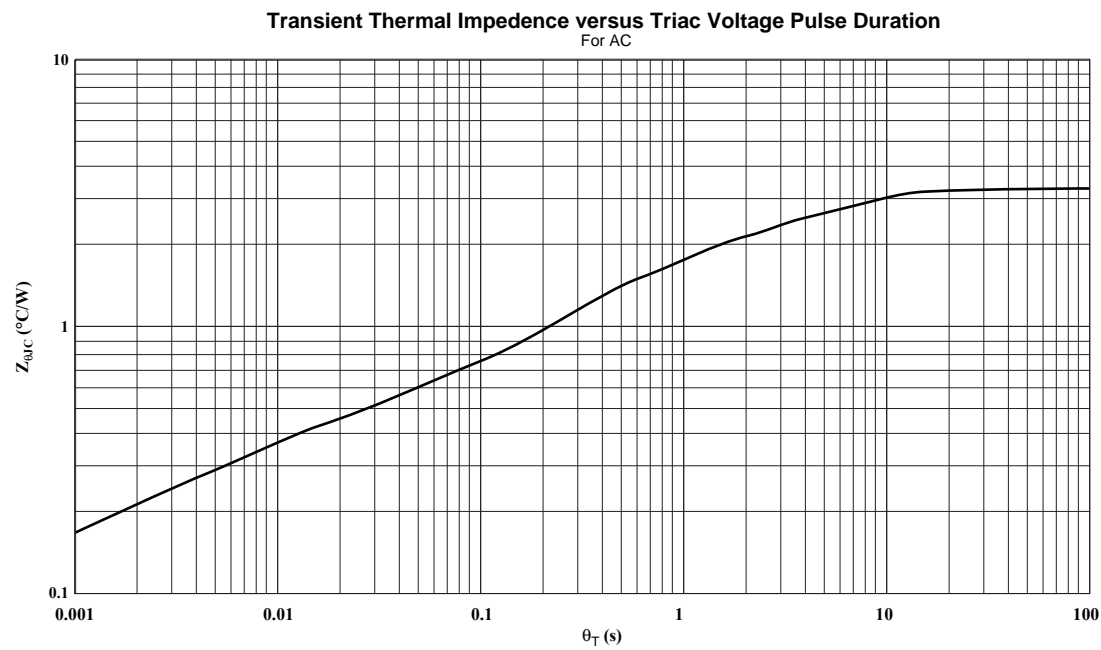
Gate Trigger Characteristics



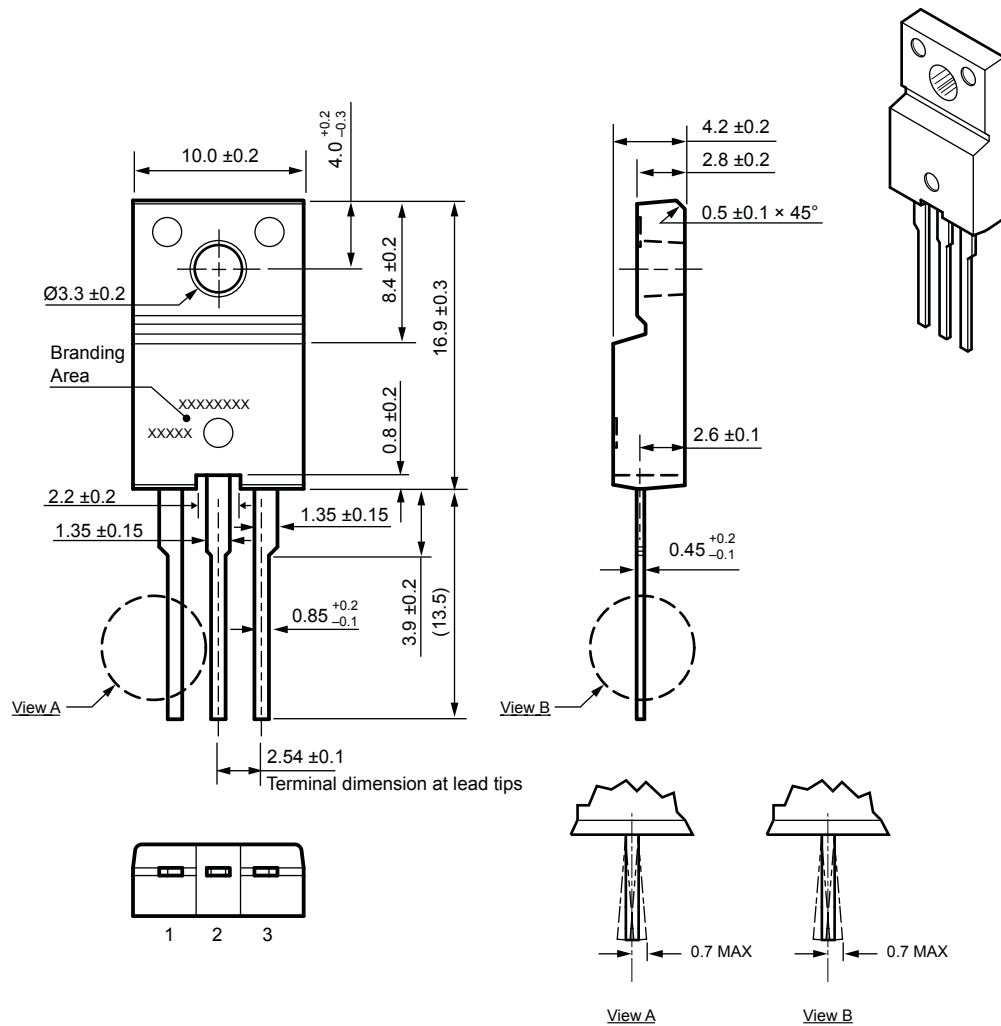
Commutation Timing Diagrams



Performance Characteristics at  $T_A = 25^\circ\text{C}$ 



## TO-220F Package Outline Drawing



Gate burr: 0.3 mm (max.), mold flash may appear at opposite side  
Terminal core material: Cu  
Terminal treatment: Ni plating and Pb-free solder dip  
Leadform: 600  
Package: TO-220F (FM20)

Branding codes (exact appearance at manufacturer discretion):  
1st line, type: MA20x  
2nd line, lot: YM  
Where: Y is the last digit of the year of manufacture  
M is the month (1 to 9, O, N, D)



Leadframe plating Pb-free. Device  
meets RoHS requirements.

Because reliability can be affected adversely by improper storage environments and handling methods, please observe the following cautions.

Cautions for Storage

- Ensure that storage conditions comply with the standard temperature (5°C to 35°C) and the standard relative humidity (around 40 to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of products that have been stored for a long time.

Cautions for Testing and Handling

When tests are carried out during inspection testing and other standard test periods, protect the products from power surges from the testing device, shorts between adjacent products, and shorts to the heatsink.

Remarks About Using Silicone Grease with a Heatsink

- When silicone grease is used in mounting this product on a heatsink, it shall be applied evenly and thinly. If more silicone grease than required is applied, it may produce stress.
- Coat the back surface of the product and both surfaces of the insulating plate to improve heat transfer between the product and the heatsink.
- Volatile-type silicone greases may permeate the product and produce cracks after long periods of time, resulting in reduced heat radiation effect, and possibly shortening the lifetime of the product.
- Our recommended silicone greases for heat radiation purposes, which will not cause any adverse effect on the product life, are indicated below:

Type	Suppliers
G746	Shin-Etsu Chemical Co., Ltd.
YG6260	Momentive Performance Materials Inc.
SC102	Dow Corning Toray Silicone Co., Ltd.

Heatsink Mounting Method

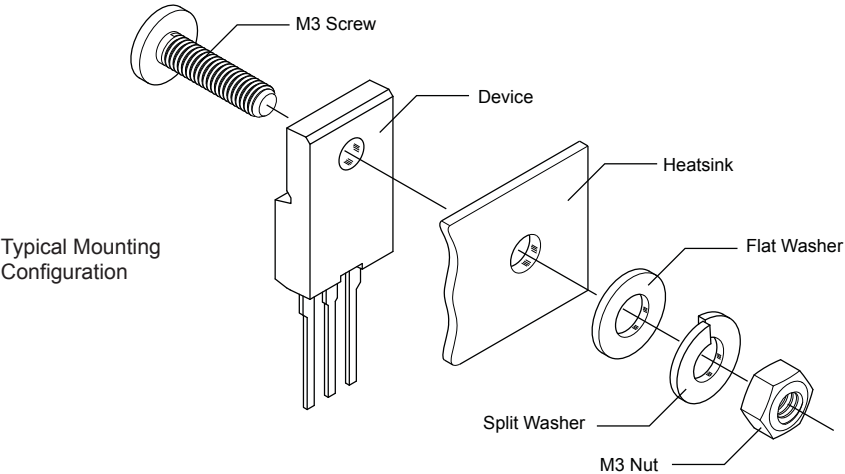
- Torque When Tightening Mounting Screws. Thermal resistance increases when tightening torque is low, and radiation effects are decreased. When the torque is too high, the screw can strip, the heatsink can be deformed, and distortion can arise in the product frame. To avoid these problems, observe the recommended tightening torques for this product package type 0.490 to 0.686 N•m (5 to 7 kgf•cm).
- For effective heat transfer, the contact area between the product and the heatsink should be free from burrs and metal fragments, and the heatsink should be flat and large enough to contact over the entire side of the product, including mounting flange and exposed thermal pad.
- The mounting hole in customer-supplied heatsink must be less than Ø4 mm; this includes the diameter of any dimple around punched holes. This is to prevent possible deflection and cracking of the product case when fastened to the heatsink.

Soldering

- When soldering the products, please be sure to minimize the working time, within the following limits:  
260±5°C 10 s  
350±5°C 3 s
- Soldering iron should be at a distance of at least 1.5 mm from the body of the products

Electrostatic Discharge

- When handling the products, operator must be grounded. Grounded wrist straps worn should have at least 1 MΩ of resistance to ground to prevent shock hazard.
- Workbenches where the products are handled should be grounded and be provided with conductive table and floor mats.
- When using measuring equipment such as a curve tracer, the equipment should be grounded.
- When soldering the products, the head of soldering irons or the solder bath must be grounded in other to prevent leak voltages generated by them from being applied to the products.
- The products should always be stored and transported in our shipping containers or conductive containers, or be wrapped in aluminum foil.





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In addition, it should be noted that since power devices or IC's including power devices have large self-heating value, the degree of derating of junction temperature affects the reliability significantly.

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